

SOT602-1

plastic thermal enhanced ball grid array package; 256 balls;
body 27 x 27 x 0.9 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA256
Package type industry code	HBGA256
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	17-3-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		26.8	-	27	27.2	mm
E	package width		26.8	-	27	27.2	mm
A	seated height		[tbd]	-	1.65	1.65	mm
A ₂	package height		0.8	-	0.9	1	mm
n ₂	actual quantity of termination		-	-	256	-	



2. Package outline

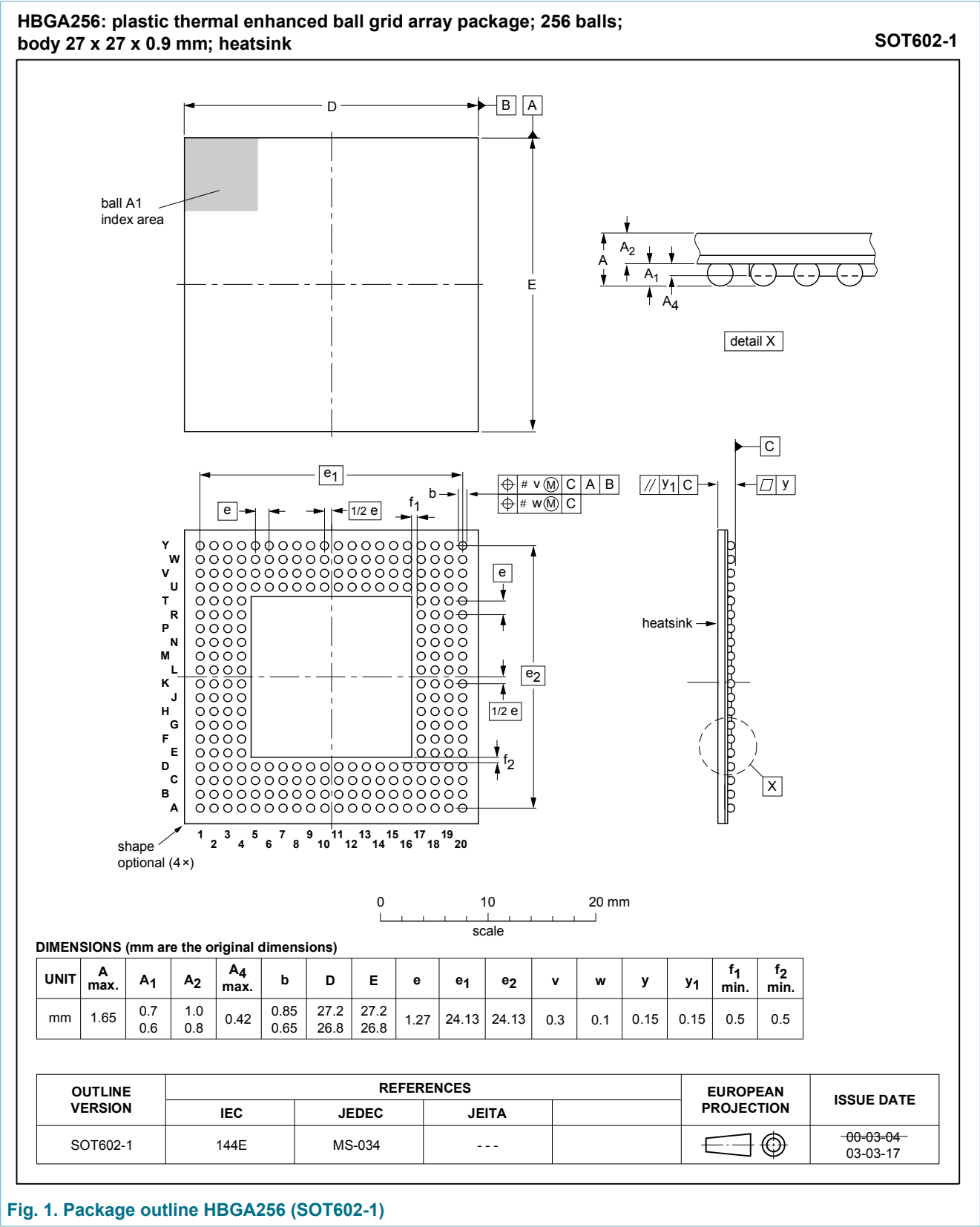


Fig. 1. Package outline HBGA256 (SOT602-1)

3. Soldering

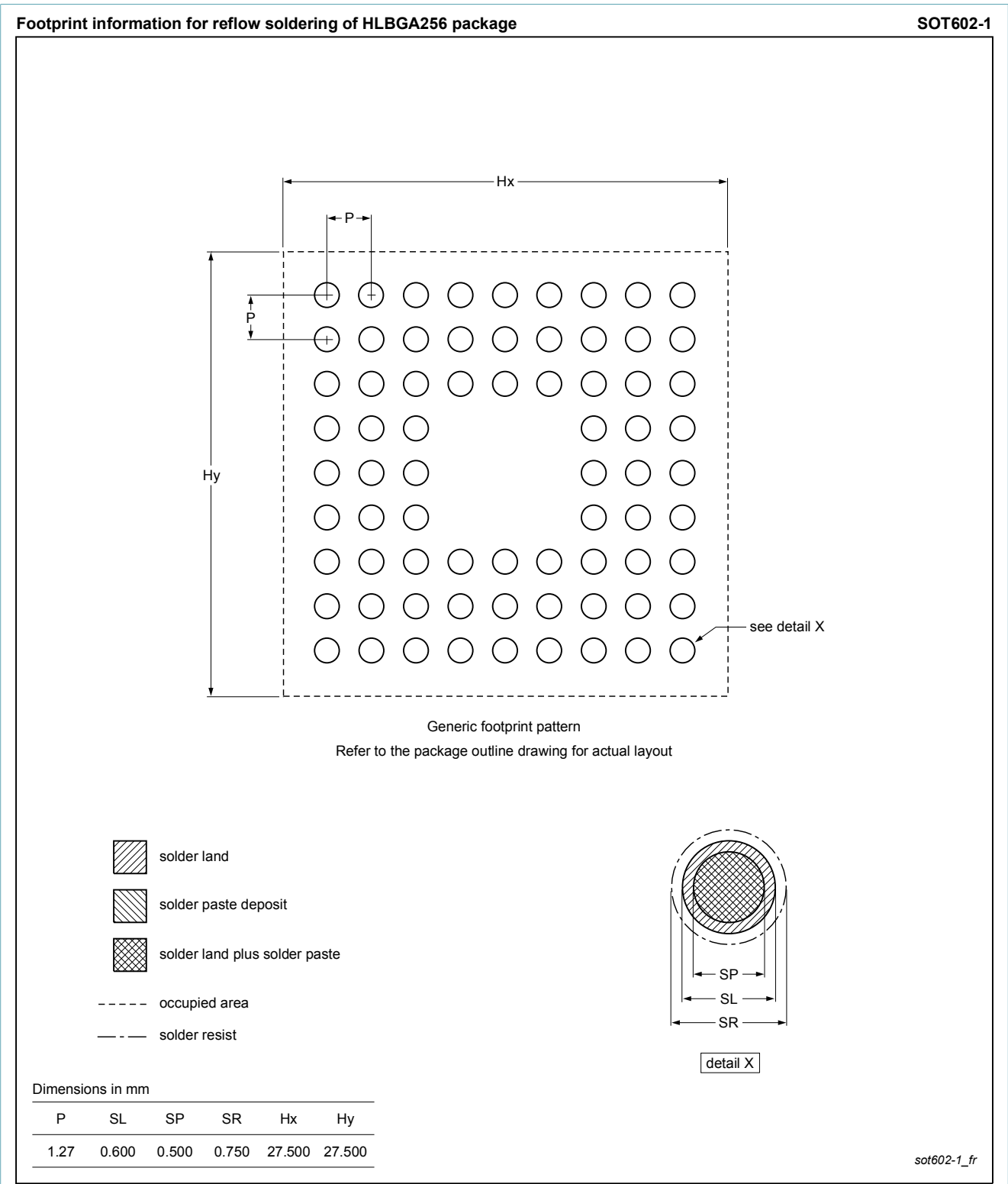


Fig. 2. Reflow soldering footprint for HLBGA256 (SOT602-1)

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4. Legal information

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